

Datasheet revision 1.1

Smooth Flow[™] Solder Paste No-Clean Sn42/Bi57.6/Ag0.4 T4 (35g Syringe)

Product Highlights

Smooth Flow[™] Technology Developed with a lower density flux vehicle for better shear spread and improved flow during heating Printing speeds up to 125mm/sec Long stencil life, Wide process window Halogen Free (EN14582 test method)

Clear residue Low voiding Excellent wetting compatibility on most board finishes Dispense grade Compatible with enclosed print heads **RoHS 3 and REACH compliant**



Specifications

Alloy:	Sn42/Bi57.6/Ag0.4	Star Star
Mesh Size:	Τ4	Non Of
Micron (µm) Range:	20-38	the second se
Flux Type:	Synthetic No-Clean	
Flux Classification:	ROL0	
Metal Load:	86.75% Metal by Weight	
Melting Point:	138°C (281°F)	
Packaging:	10cc/35g Syringe	-
Shelf Life:	Refrigerated >6 months, Unrefrigerated >2 months	*See notes below:

*Shelf Life Notes: Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using Made in USA high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

Printer Operation

Print Speed: 25-125mm/sec Squeegee Pressure: 70-250g/cm of blade Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

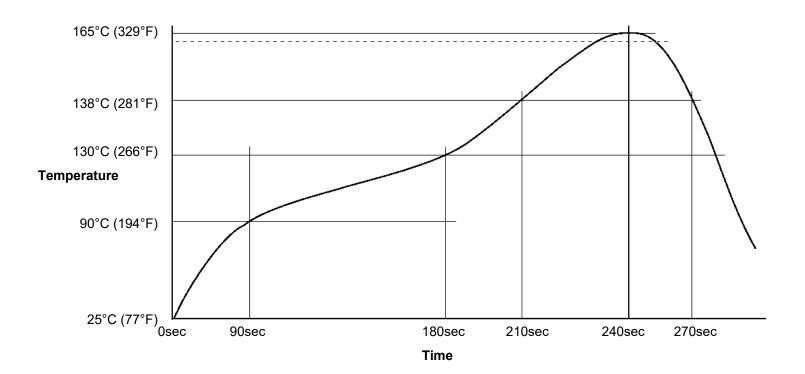
Storage and Handling

Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Reflow profile for Sn42/Bi57.6/Ag0.4 solder assembly, designed as a starting point for process optimization.



Test Results

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Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Tack Value	IPC-TM-650: 2.4.44	34g
Viscosity – Malcom @ 10 RPM/25°C (x10 ³ mPa/s)	IPC-TM-650: 2.4.34.4	Print: 130-185, Dispense: 105-150
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): RoHS 3 Directive (EU) 2015/863:	Yes Yes